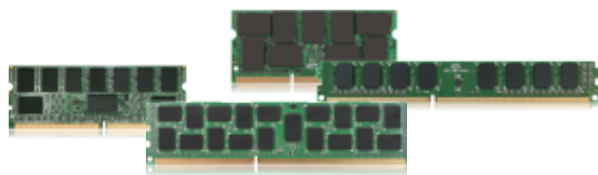




ATP DDR3 DRAM Solutions

Intense Performance for Intense Workloads



Operating at 1.5V (normal) and 1.35V (low voltage) and with a transfer speed of up to 1866 MT/s, ATP DDR3 modules deliver better performance while consuming significantly less power than DDR2 memory.

ATP DDR3 modules are supported by the Intel® Core™ i7 Series, the AMD AM3 Phenom™ processor, and the latest AMD Embedded Enterprise Chipsets. DDR3 modules are not pin-compatible with the prior-generation modules and have alignment notches preventing them from being inserted into incompatible slots.

ATP offers DDR3 SDRAMs in a wide range of form factors and features including SO-DIMM and Mini-DIMM with low profile, very low profile (VLP) and ultra-low profile (ULP) options.

In addition to standard offerings, ATP's DDR3 product line has enhanced reliability options such as conformal coating for protection against dust, chemicals, extreme temperatures and corrosion. The 30μ" thickness of the gold finger plating ensures better durability and signal transmission quality.

Key Features

- Density: 1 GB to 32 GB
- Chipkill support
- Fly-by command/address/control bus with on-DIMM termination
- Higher bandwidth performance, effectively up to 1866 MT/s
- Better performance at low power; 1.5V (Normal) and 1.35V (Low Voltage)

Applications

- The Internet of Things (IoT)
- Networking systems
- Telecommunication
- Gaming
- Healthcare
- Industrial PCs
- Micro servers



Specifications

DDR3					
Type	LRDIMM	RDIMM	UDIMM	ECC UDIMM	SO-RDIMM
Data Rate Speed (MT/s)	1600 1333 1066	1866 1600 1333 1066	1866 1600 1333 1066	1866 1600 1333 1066	1600 1333 1066
Density	32GB	1 GB / 2 GB / 4 GB / 8 GB / 16 GB / 32 GB	1 GB / 2GB / 4 GB / 8 GB / 16 GB	1 GB / 2 GB / 4 GB / 8 GB / 16 GB	2 GB / 4 GB / 8 GB
Voltage	1.35V / 1.5V				
PCB Height	▪ Low profile	▪ Low profile ▪ VLP options: 0.74" height ▪ ULP options: below 0.74" height	▪ Low profile ▪ VLP options: 0.74" height	▪ Low profile ▪ VLP options: 0.74" height	▪ Low profile
Working Temperature	0-85°C / -40-95°C				
Golden Finger	30μ				

DDR3				
Type	SODIMM	ECC SODIMM	Mini-RDIMM	ECC Mini-UDIMM
Data Rate Speed (MT/s)	1866 1600 1333 1066	1866 1600 1333 1066	1600 1333 1066	1600 1333 1066
Density	1 GB / 2 GB / 4 GB / 8 GB / 16 GB	1 GB / 2 GB / 4 GB / 8 GB / 16 GB	2 GB / 4 GB / 8 GB / 16GB	2 GB / 4 GB / 8 GB / 16 GB
Voltage	1.35V / 1.5V			
PCB Height	▪ Low profile	▪ Low profile	▪ Low profile ▪ VLP options: 0.74" height ▪ ULP options: below 0.74" height	▪ Low profile ▪ VLP options: 0.74" height ▪ ULP options: below 0.74" height
Working Temperature	0-85°C / -40-95°C			
Golden Finger	30μ			

ATP Global Footprint

To learn more about this product, contact your ATP Representative.

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